

B1  
Conced

a film comprising an organic material covering said EL element; and  
a film comprising an inorganic material covering said film comprising an organic material.

4. (Amended) A self-light emitting device comprising:  
an EL element comprising a first electrode, a light emitting layer over the first electrode, and a second electrode over the light emitting layer;  
a film comprising an organic material in contact with said EL element; and  
a film comprising an inorganic material in contact with said film comprising an organic material.

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17. (Amended) A method of manufacturing a self-light emitting device comprising:  
forming an EL element comprising a first electrode, a light emitting layer over the first electrode, and a second electrode over the light emitting layer;  
forming a film comprising an inorganic material covering said EL element by using a CVD method or an evaporation method; and  
forming a film comprising an organic material covering said film comprising said inorganic material by using an ink jet method.

18. (Amended) A method of manufacturing a self-light emitting device comprising:  
forming an EL element comprising a first electrode, a light emitting layer over the first electrode, and a second electrode over the light emitting layer;  
forming a film comprising an organic material covering said EL element by using an ink jet method; and  
forming a film comprising an inorganic material covering said film comprising said organic material by using a CVD method or an evaporation method. --

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**Please add new claims 23-26:**

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-- 23. (New) A method of manufacturing a light emitting device comprising:  
forming an EL element comprising a first electrode, a light emitting layer over the first electrode, and a second electrode over the light emitting layer;  
forming a film comprising an inorganic material covering said EL element by using a CVD method or an evaporation method; and  
forming a film comprising an organic material covering said film comprising said inorganic material by using an ink jet method,  
wherein said light emitting layer, said second electrode, said film comprising an inorganic material, and said film comprising an organic material are formed continuously using the same film deposition apparatus.

24. (New) A method of manufacturing a light emitting device comprising:  
forming an EL element comprising a first electrode, a light emitting layer over the first electrode, and a second electrode over the light emitting layer;  
forming a film comprising an organic material covering said EL element by using an ink jet method; and  
forming a film comprising an inorganic material covering said film comprising said organic material by using a CVD method or an evaporation method,  
wherein said light emitting layer, said second electrode, said film comprising an inorganic material, and said film comprising an organic material are formed continuously using the same film deposition apparatus.

25. (New) A method of manufacturing a light emitting device comprising:  
forming an EL element comprising a first electrode, a light emitting layer over the first electrode, and a second electrode over the light emitting layer;  
forming a film comprising an inorganic material covering said EL element; and  
forming a film comprising an organic material covering said film comprising said inorganic material,

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wherein said light emitting layer and said film comprising an organic material are formed using the same film deposition method.

26. (New) A method of manufacturing a light emitting device comprising:  
forming an EL element comprising a first electrode, a light emitting layer over the first electrode, and a second electrode over the light emitting layer;  
forming a film comprising an organic material covering said EL element; and  
forming a film comprising an inorganic material covering said film comprising said organic material,

wherein said light emitting layer and said film comprising an inorganic are formed using the same film deposition method. --

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